

N-Channel 40-V (D-S) MOSFET

Key Features:

- Low $r_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed

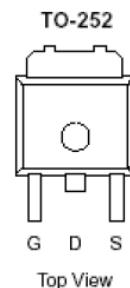
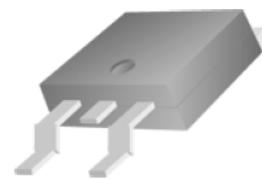
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (mΩ)	I_D (A)
40	12 @ $V_{GS} = 10V$	53
	14 @ $V_{GS} = 4.5V$	49

Typical Applications:

- White LED boost converters
- Automotive Systems
- Industrial DC/DC Conversion Circuits



RoHS
COMPLIANT
HALOGEN
FREE



Top View

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Limit	Units
Drain-Source Voltage	$T_A = 25^\circ C$	V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_A = 25^\circ C$	I_D	53	A
Pulsed Drain Current ^b		I_{DM}	200	
Continuous Source Current (Diode Conduction) ^a		I_S	44	A
Power Dissipation ^a	$T_A = 25^\circ C$	P_D	50	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$T_A = 25^\circ C$	$R_{\theta JA}$	40	°C/W
Maximum Junction-to-Case		$R_{\theta JC}$	3	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

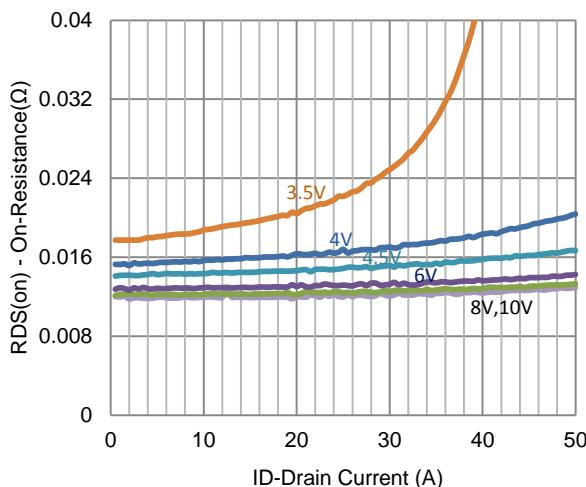
Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 32 V$, $V_{GS} = 0 V$			1	uA
		$V_{DS} = 32 V$, $V_{GS} = 0 V$, $T_J = 55^\circ C$			25	
On-State Drain Current	$I_{D(on)}$	$V_{DS} = 5 V$, $V_{GS} = 10 V$	100			A
Drain-Source On-Resistance	$r_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 20 A$			12	mΩ
		$V_{GS} = 4.5 V$, $I_D = 16 A$			14	
Forward Transconductance	g_{fs}	$V_{DS} = 15 V$, $I_D = 20 A$		20		S
Diode Forward Voltage	V_{SD}	$I_S = 22 A$, $V_{GS} = 0 V$		0.97		V
Dynamic						
Total Gate Charge	Q_g	$V_{DS} = 20 V$, $V_{GS} = 4.5 V$, $I_D = 20 A$		19		nC
Gate-Source Charge	Q_{gs}			5.5		
Gate-Drain Charge	Q_{gd}			10		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 20 V$, $R_L = 1 \Omega$, $I_D = 20 A$, $V_{GEN} = 10 V$, $R_{GEN} = 6 \Omega$		8		ns
Rise Time	t_r			11		
Turn-Off Delay Time	$t_{d(off)}$			52		
Fall Time	t_f			22		
Input Capacitance	C_{iss}	$V_{DS} = 15 V$, $V_{GS} = 0 V$, $f = 1 MHz$		1826		pF
Output Capacitance	C_{oss}			253		
Reverse Transfer Capacitance	C_{rss}			209		

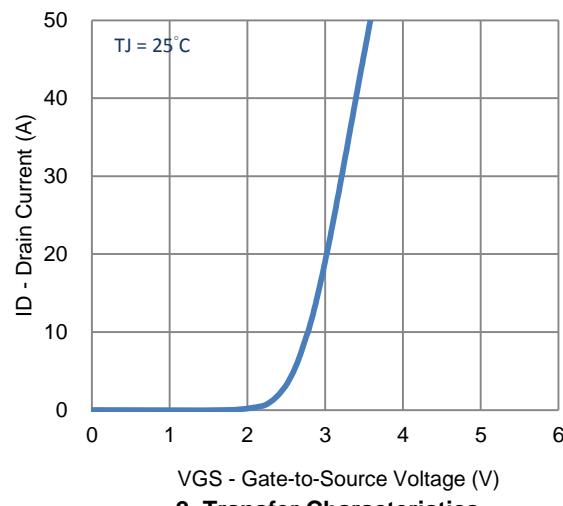
Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

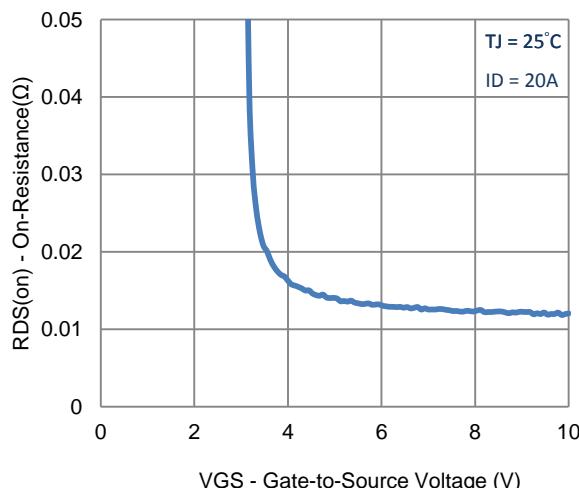
Typical Electrical Characteristics



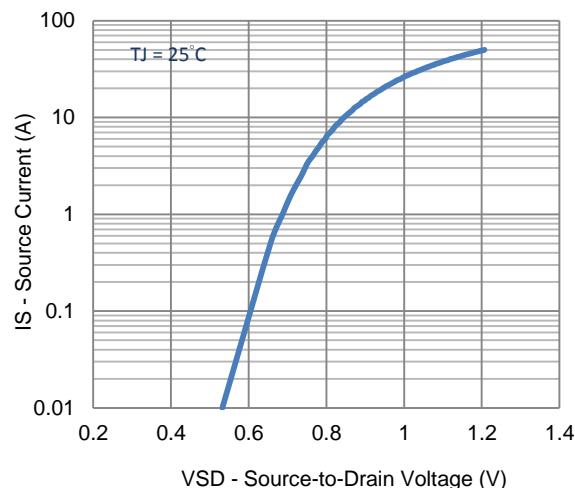
1. On-Resistance vs. Drain Current



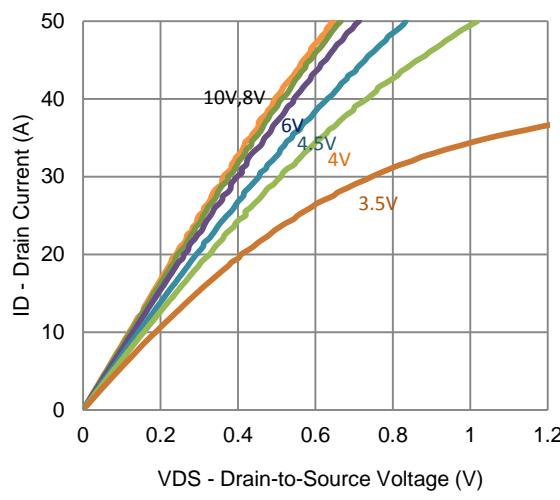
2. Transfer Characteristics



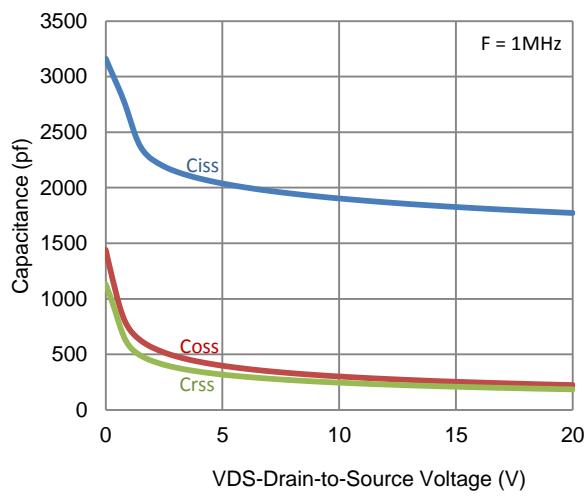
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

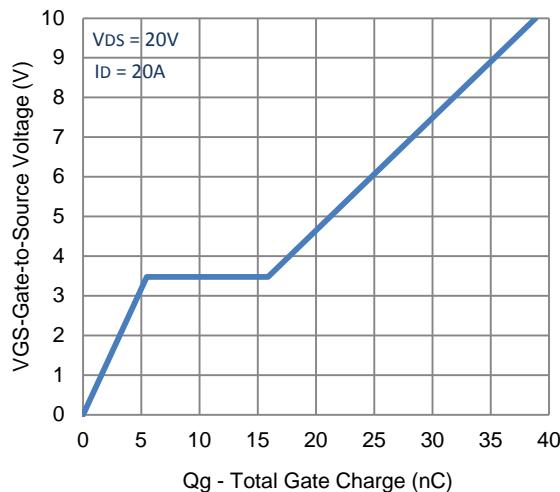


5. Output Characteristics

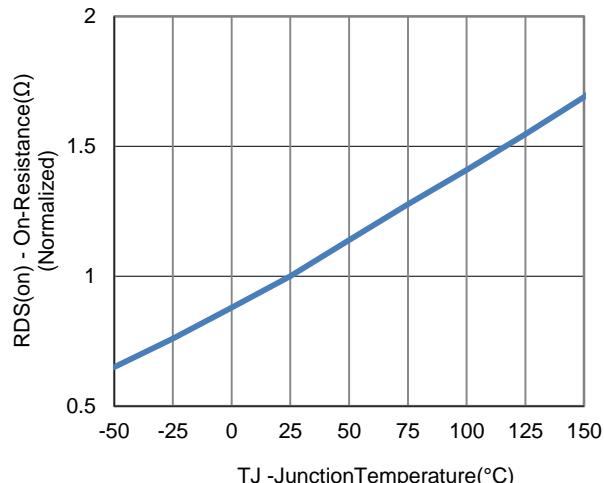


6. Capacitance

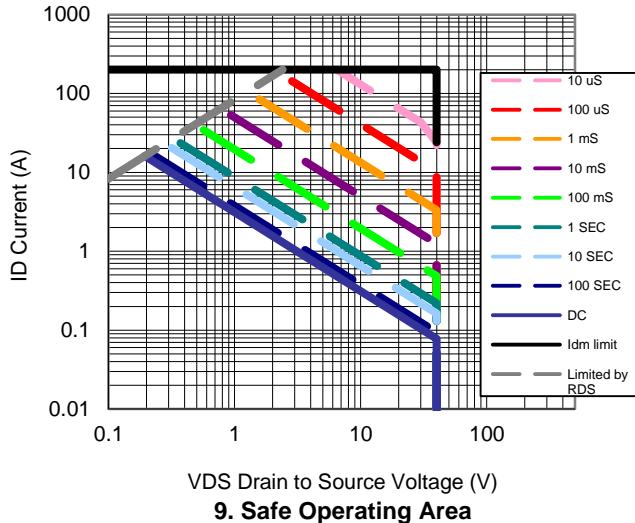
Typical Electrical Characteristics



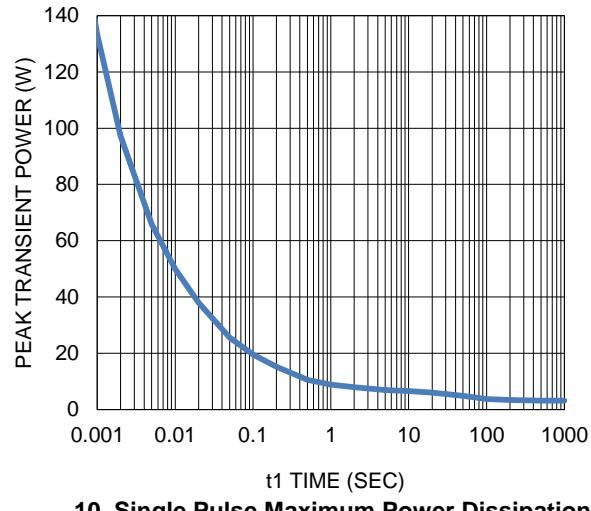
7. Gate Charge



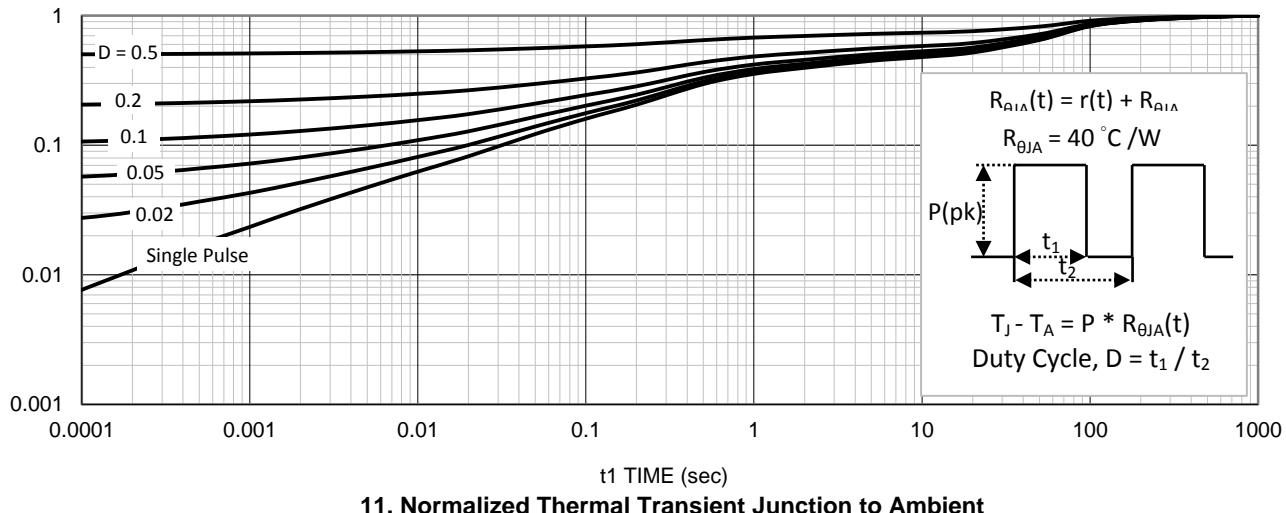
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

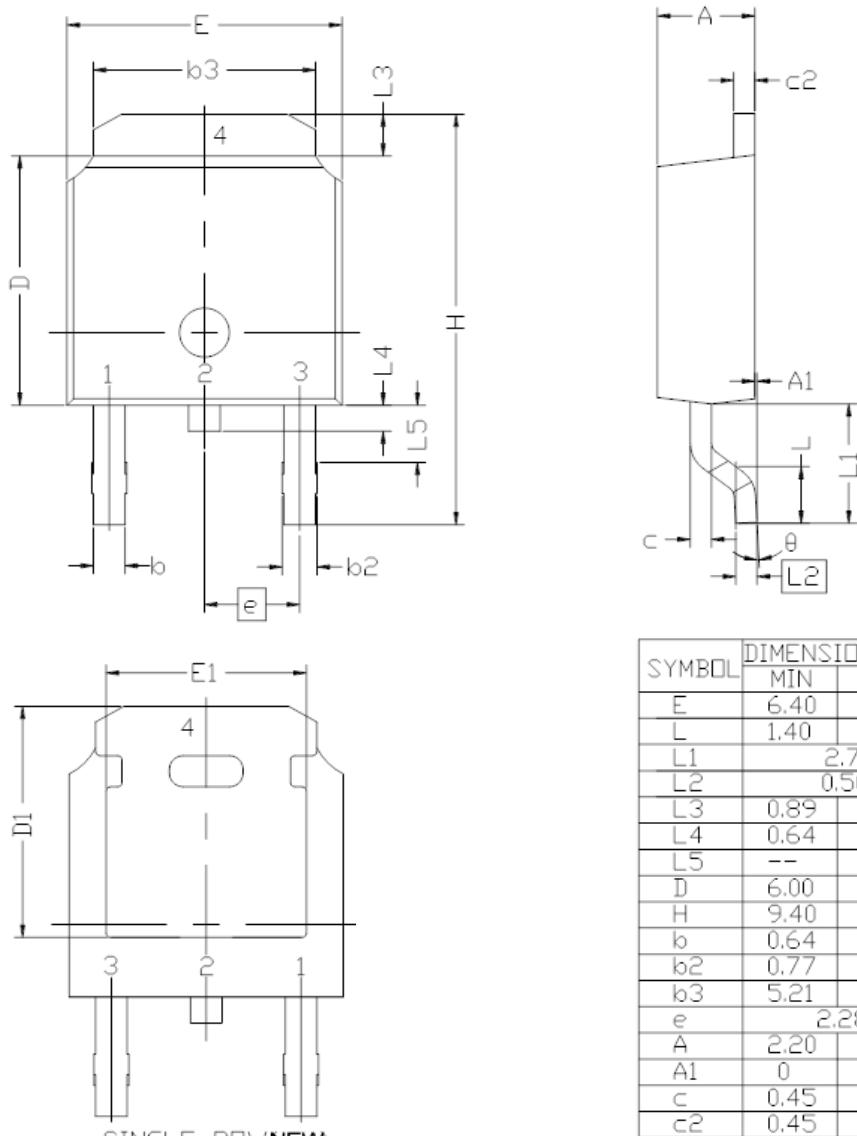


10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient

Package Information



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1		2.743	REF
L2		0.508	BSC
L3	0.89	--	1.27
L4	0.64	--	1.01
L5	--	--	--
D	6.00	6.10	6.223
H	9.40	10.00	10.40
b	0.64	0.76	0.88
b2	0.77	0.84	1.14
b3	5.21	5.34	5.46
e		2.286	BSC
A	2.20	2.30	2.38
A1	0	--	0.127
c	0.45	0.50	0.60
c2	0.45	0.50	0.58
D1	5.30	--	--
E1	4.40	--	--
theta	0°	--	10°

Note:

1. All Dimension Are In mm.
2. Package Body Sizes Exclude Mold Flash, Protrusion Or Gate Burrs. Mold Flash, Protrusion Or Gate Burrs Shall Not Exceed 0.10 mm Per Side.
3. Package Body Sizes Determined At The Outermost Extremes Of The Plastic Body Exclusive Of Mold Flash, Gate Burrs And Interlead Flash, But Including Any Mismatch Between The Top And Bottom Of The Plastic Body.